

ABSTRACT

In a method of manufacturing a semiconductor device comprising: a first wiring extending in a first direction; and a second wiring connected to the first wiring through a connection and extending in a second direction orthogonal to the first direction, the second wiring having a surplus portion projecting from the connection in a direction opposite to the second direction, the first and second wirings are arranged such that a center of the connection is offset in the second direction from a center of the first wiring, and a projecting portion of the first wiring is disposed under the connection.